

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Han Sub HWANG</td><td>10/11/2007</td></tr><tr><td>Sung Ki KIM</td><td>10/11/2007</td></tr><tr><td>Sang Hun LEE</td><td>10/11/2007</td></tr><tr><td>Jong Won LEE</td><td>10/11/2007</td></tr></tbody></table>	Name	Execution Date	Han Sub HWANG	10/11/2007	Sung Ki KIM	10/11/2007	Sang Hun LEE	10/11/2007	Jong Won LEE	10/11/2007	
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Han Sub HWANG	10/11/2007										
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Sang Hun LEE	10/11/2007										
Jong Won LEE	10/11/2007										
RECEIVING PARTY DATA											
Name:	Samsung Electronics Co., Ltd.										
Street Address:	416, Maetan-dong, Yeongtong-gu,										
Internal Address:	Gyeonggi-do,										
City:	Suwon-si										
State/Country:	KOREA, REPUBLIC OF										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11874302</td></tr></tbody></table>	Property Type	Number	Application Number:	11874302							
Property Type	Number										
Application Number:	11874302										
CORRESPONDENCE DATA											
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Total Attachments: 1 source=ASSIGNMENT#page1.tif											

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PATENT

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## Assignment


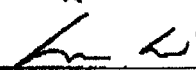

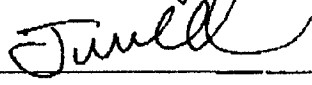
Whereas, We, Han Sub HWANG, Sung Ki MIN, Sang Hun LEE, and Jong Won LEE of Suwon-si, Republic of Korea, Suwon-si, Republic of Korea, Seoul, Republic of Korea, and Seoul, Republic of Korea, respectively, hereinafter called assignors, have invented certain improvements in INJECTION MOLDING APPARATUS and executed an application for Letters Patent of the United States of America therefor on \_\_\_\_\_; and

Whereas, SAMSUNG ELECTRONICS CO., LTD., 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea (assignee), desires to acquire the entire right, title, and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

We, the above named assignors, hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including the right to claim priority under 35 U.S.C. §119, and we request the Director of the U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States application when called upon to do so by the assignee.

We hereby authorize and request our attorneys SUGHRUE MION, PLLC of 2100 Pennsylvania Avenue, NW, Washington, DC 20037-3213 to insert here in parentheses (Application number \_\_\_\_\_ and Confirmation number \_\_\_\_\_, filed \_\_\_\_\_) the application number and filing date of said application when known.

Date:	October 11, 2007	
	s/Han Sub HWANG	
Date:	October 11, 2007	
	s/Sung Ki KIM	
Date:	October 11, 2007	
	s/Sang Hun LEE	
Date:	Oct. 11, 2007	
	s/Jong Won LEE	

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. §261)